

Amendments to the Specification

Please substitute the following annotated paragraph for the paragraph beginning on page 9, line 9:

Fig. 4 illustrates the logic relations of the assessment engine 130 of the reliability assessment system 100 according to the present invention. For a semiconductor product, the assessment engine 130 receives the technology 131, such as the geometry or generation, and specifications 132 of the product, such as processes employed, including GOI (gate oxide integrity), HCI (hot carrier injection), NBTI (negative bias temperature instability), EM (electromigration) and IMD(intermetal dielectric)-TDDB (time dependent dielectric breakdown), voltage, temperature, area, transistor size, metal dimension, lifetime, burn-in, die size, and others, performing the reliability assessment accordingly, to generate the result 133.